

4

3

2

1

D

D

C

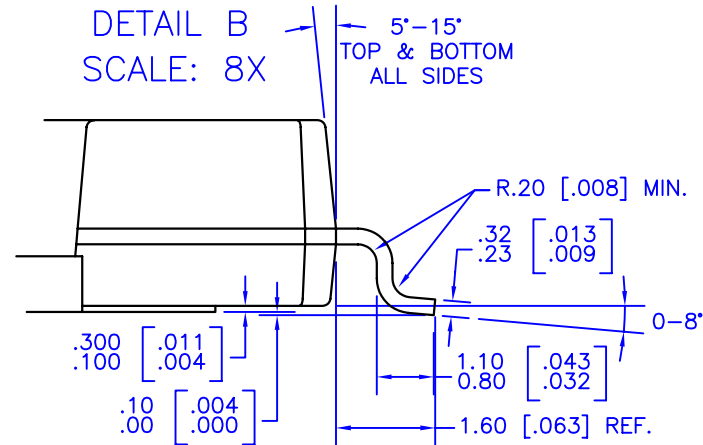
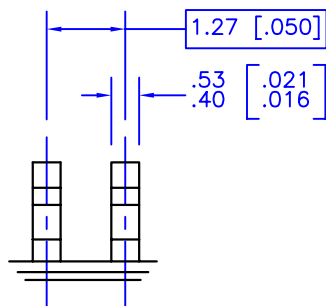
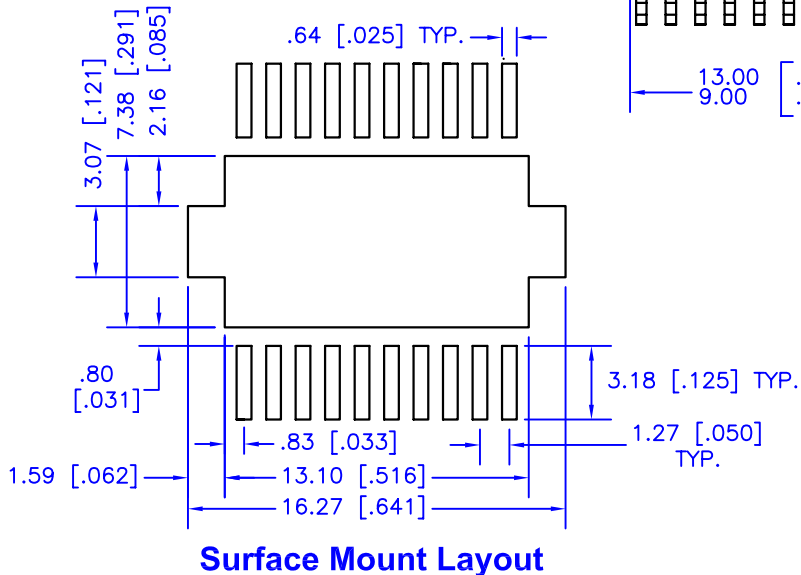
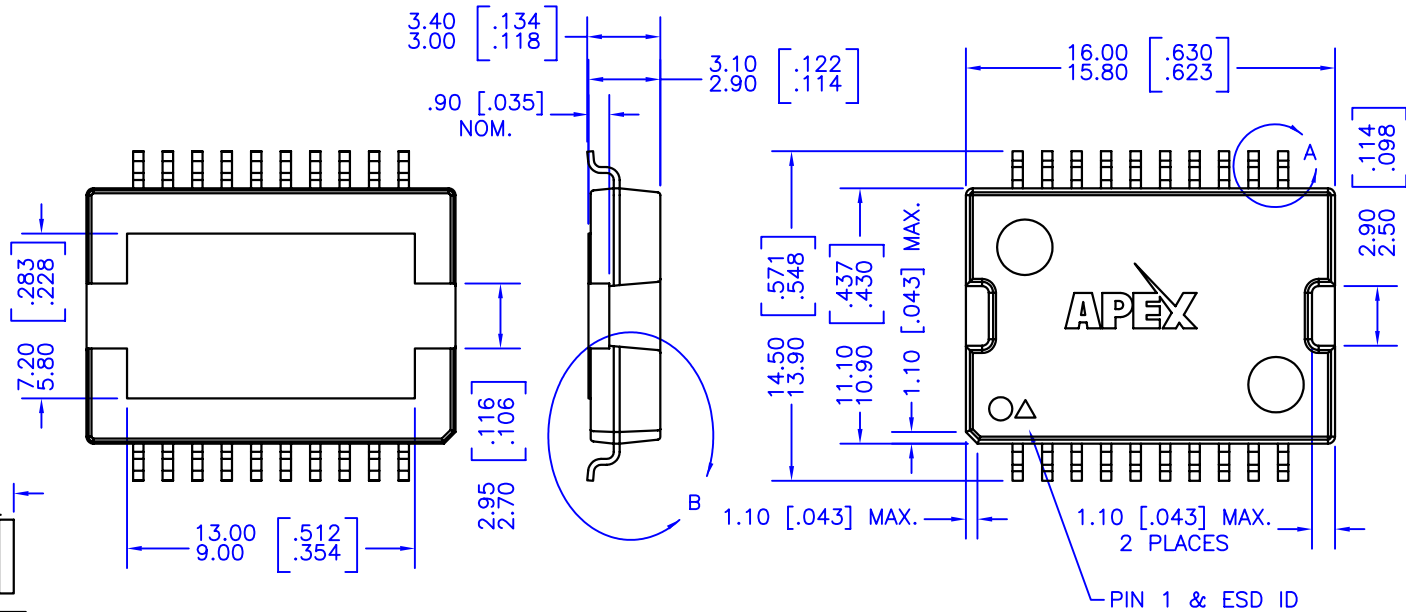
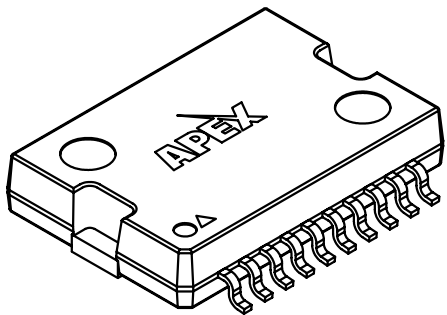
C

B

B

A

A



NOTES:

- Dimensions are millimeters & [inches].
- Bracketed alternate units are for reference only.
- Dimple on lid & ESD triangle denote pin 1.
- Heat Slug: C19400 copper with Sn-Bi plating or C10200 copper with Ni-Pd-Au plating
- Lead frame: C19400 copper with Sn-Bi or Ni-Pd-Au plating.
- Mold compound: MP-8000AN or EME6600HR epoxy
- Package weight: .086 oz. [2.44 g]
- Suggested surface mount layout for reference only.

TOLERANCES - UNLESS OTHERWISE SPECIFIED	
.XX	= ±.01 [.254]
.XXX	= ±.005 [.127]
ANG.	= ±.5°



TITLE		20-PIN PSOP (JEDEC MO-166)		PACKAGE	
SUBJECT		MECHANICAL PACKAGE OUTLINE		DK	
ENG:	TECH/DRAW:	DCA:	SHL:	OF:	FILENAME:
D-M	D-M	60061	1	1	DK

REV	DATE
D	02/02/06

4

3

2

1